

AMENDMENTS TO THE CLAIMS

1. (Previously Presented) A print head die forming method comprising:
forming a plurality of fluid-handling passageways and ejection chambers over a first surface of a substrate;
subsequent to said forming a plurality of fluid-handling passageways and ejection chambers, forming a first patterned masking layer sufficient to expose a desired area of a second generally opposing surface of the substrate;
after forming the first patterned masking layer, forming a second patterned masking layer sufficient to expose less than the entirety of the desired area of the second surface;
forming a slot portion in the substrate through the second patterned masking layer; and
removing additional substrate material to form a fluid-handling slot sufficient to supply fluid from the second surface through the substrate to the first surface and the fluid handling passageways, the fluid-handling slot extending along a long axis that lies generally parallel to the first surface, wherein the fluid-handling slot has a cross-section taken transverse the long axis that is defined, at least in part, by one sidewall, wherein at least a first portion of the one sidewall is generally parallel to the first surface, and wherein a second portion of the one sidewall is generally perpendicular to the first surface, and wherein a third portion of the sidewall extends from the second portion to and in contact with the first surface of the substrate and defines an obtuse angle with the second portion as measured through the fluid-handling slot.
2. (Original) The method of claim 1, wherein said act of forming a first patterned masking layer comprises forming a hard mask.
3. (Original) The method of claim 1, wherein said act of forming a second patterned masking layer comprises forming a photo-resist layer.
4. (Original) The method of claim 1, wherein said act of forming a slot portion comprises etching the slot portion.

5. (Original) The method of claim 1, wherein said act of removing forms a fluid-handling slot having a through region positioned between two shallow regions.

6. (Original) The method of claim 1, wherein said act of removing comprises wet etching the additional substrate material.

7. (Original) The method of claim 1 further comprising, after said act of forming a slot portion and before removing the additional substrate material, removing a portion of the second patterned masking layer.

8. (Canceled)

9. (Previously Presented) A fluid-feed slot forming method comprising:
forming a plurality of fluid-handling passageways and ejection chambers over a first substrate surface;

subsequent to said forming a plurality of fluid-handling passageways and ejection chambers over a first substrate surface, patterning a hard mask on a generally opposing second substrate sufficient to expose a first area of the second surface;

forming a slot portion in the substrate through less than an entirety of the first area of the second surface, the slot portion having a cross-sectional area at the second surface that is less than a cross-sectional area of the first area; and

after forming the slot portion, etching the substrate to remove material from within the first area to form a fluid-handling slot between the first and second surfaces sufficient to supply fluid to the fluid handling passageways, the fluid-handling slot extending along a long axis that lies generally parallel to the first substrate surface, wherein the fluid-handling slot has a cross-section taken transverse the long axis that is defined, at least in part, by one sidewall, wherein at least a first portion of the one sidewall is generally parallel to the first substrate surface, and wherein a second portion of the one sidewall is generally perpendicular to the first substrate surface, and wherein a third portion of the sidewall extends from the second portion to and in contact with the first substrate surface of the substrate and defines an obtuse angle with the second portion as measured through the fluid-

handling slot.

10. (Original) The method of claim 9, wherein said act of forming a slot portion forms a slot portion having a cross-sectional area that comprises a subset of the first area.

11. (Previously Presented) The method of claim 9, wherein said act of patterning a hard mask comprises covering the entire second substrate surface with the hard mask and subsequently removing hard mask material from the first area of the surface.

12. (Canceled)

13. (Previously Presented) A print head substrate forming method comprising:
forming a plurality of fluid-handling passageways and ejection chambers over a first substrate surface;

subsequent to said forming a plurality of fluid-handling passageways and ejection chambers, exposing a first portion of a second generally opposing substrate surface through a hard mask;

forming a photoresist over the hard mask and the first portion;

removing at least some of the photoresist to expose a second portion of the substrate surface through which a slot portion is to be formed;

dry etching the substrate through the photoresist sufficient to form the slot portion, and,

after said dry etching, wet etching the substrate to form a fluid-handling slot through the substrate to supply fluid received at the second surface through the substrate and to the fluid-handling passageways and ejection chambers via the slot portion, the fluid-handling slot extending along a long axis that lies generally parallel to the first substrate surface, wherein the fluid-handling slot has a cross-section taken transverse the long axis that is defined, at least in part, by one sidewall, wherein at least a first portion of the one sidewall is generally parallel to the first substrate surface, and wherein a second portion of the one sidewall is generally perpendicular to the first substrate surface, and wherein a third portion of the

sidewall extends from the second portion to and in contact with the first substrate surface of the substrate and defines an obtuse angle with the second portion as measured through the fluid-handling slot.

14. (Original) The method of claim 13, wherein said act of exposing comprises applying a hard mask over the entire substrate surface and removing hard mask material from over the first portion.

15. (Original) The method of claim 13, wherein said act of removing exposes a second portion that comprises a subset of the first portion.

16. (Original) The method of claim 13, wherein said act of removing exposes a second portion having an area that is less than an area of the first portion.

17. (Original) The method of claim 13, wherein said act of exposing comprises forming a hard mask over less than an entirety of the first surface.

18. (Original) The method of claim 13, wherein said act of wet etching comprises anisotropically etching the slot.

19. (Original) The method of claim 13, wherein said act of dry etching comprises alternating acts of etching and passivating.

20. (Canceled)

21. (Previously Presented) A print head forming method comprising:
forming a fluid-handling slot extending between a thin-film surface of a substrate and a generally opposing backside surface of the substrate; the slot extending along a long axis that lies generally parallel to the thin-film surface, wherein the slot has a cross-section taken transverse the long axis that is defined, at least in part, by one sidewall, wherein at least a first portion of the one sidewall is generally parallel to the thin-film surface of the substrate, and wherein a second portion of the one sidewall is generally perpendicular to the thin-film surface, and

wherein a third portion of the sidewall extends from the second portion to the and in contact with the thin-film surface of the substrate and defines an obtuse angle with the second portion as measured through the slot.

22. (Previously Presented) The method of claim 21, wherein said act of forming a fluid-handling slot in a substrate comprises:

forming a slot portion into the backside surface of the substrate; and,
etching the substrate to remove substrate material proximate the slot portion to form the fluid-handling slot.

23. (Original) The method of claim 22, wherein said act of forming a slot portion comprises one or more of: laser machining and mechanically cutting.

24. (Original) The method of claim 22, wherein said act of forming a slot portion comprises multiple removal steps.

25. (Original) The method of claim 24, wherein at least one of the multiple removal steps comprises dry etching.

26. (Original) The method of claim 24, wherein at least one of the multiple removal steps comprises patterning a hard mask.

27. (Original) The method of claim 26, wherein said act of patterning a hard mask comprises a lift-off process.

28. (Original) The method of claim 22, wherein said act of etching comprises wet etching.

29. (Canceled)

30-32. (Canceled)